TAYCHIPST

SURFACE MOUNT GENERAL PURPOSE RECTIFIERS

GS2A THRU GS2M

50V-1000V 2.0A

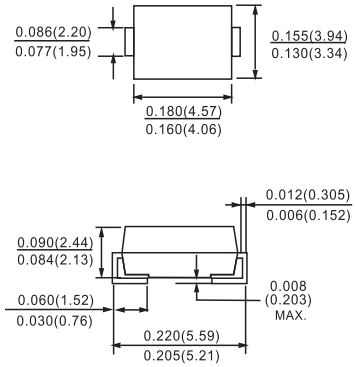
FEATURES

The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
For surface mounted applications
Low reverse leakage
Built-in strain relief,ideal for automated placement
High forward surge current capability
High temperature soldering guaranteed:
250℃/10 seconds at terminals
Glass passivated chip junction

MECHANICAL DATA

Case: JEDEC DO-214AA molded plastic body over passivated chip
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.007 ounce, 0.25grams

DO-214AA(SMB)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	GS2A	GS2B	GS2D	GS2G	GS2J	GS2K	GS2M	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at T_L=110℃	$I_{(AV)}$	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60.0							Amps
Maximum instantaneous forward voltage at 2.0A	V_F	1.1							Volts
Maximum DC reverse current T_A=25℃ at rated DC blocking voltage T_A=100℃	I_R	5.0 50.0							μA
Typical junction capacitance (NOTE 1)	C_J	30.0							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50.0							°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-65 to +175							°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2″(5.0x5.0mm) copper pad areas

FIG. 1- FORWARD CURRENT DERATING CURVE

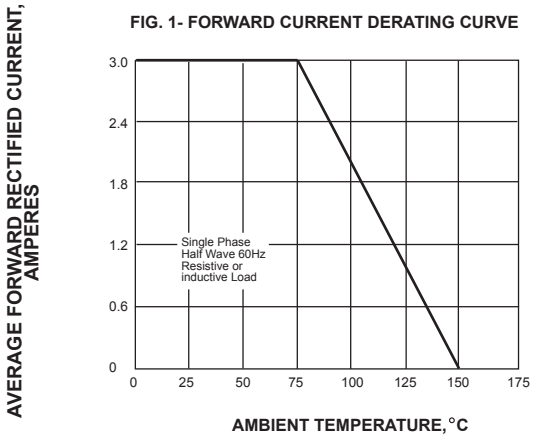


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

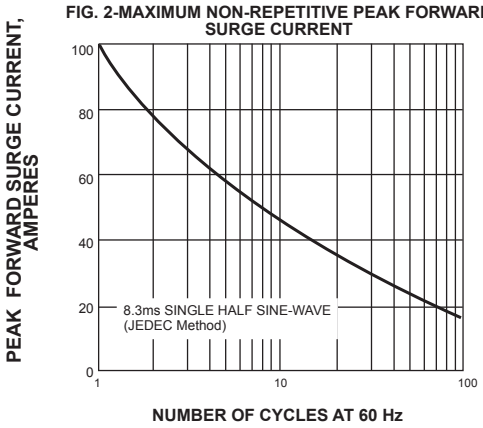


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

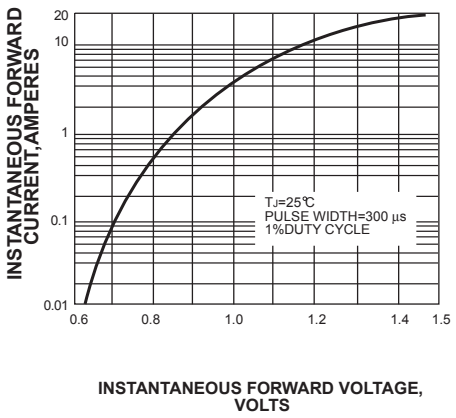


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

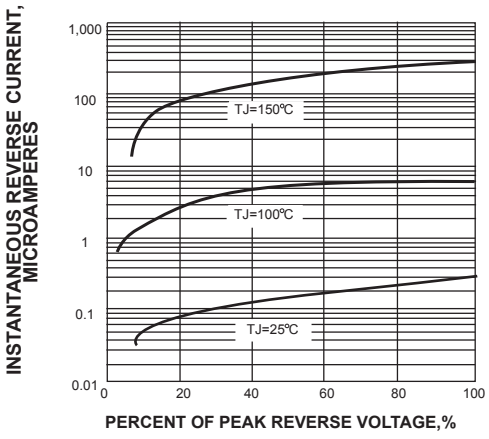


FIG. 5-TYPICAL JUNCTION CAPACITANCE

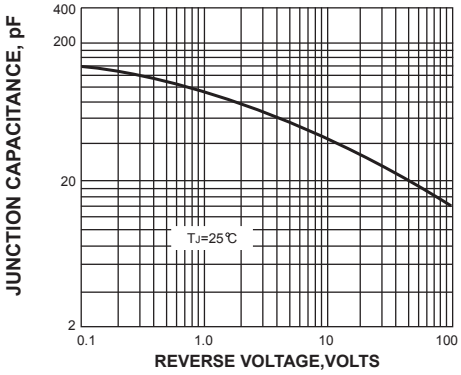


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE